

C

| Fig. | Description | Dimensions - Inch (mm) L x W x H | Thermal Res. C/Watt | Digi-Key Part No. | Price Each | | | CTS Part No. | |
|------------------------------------|--|---|------------------------------------|----------------------|-------------|------|------|-------------------|-------------------|
| | | | | | 1 | 10 | 100 | | |
| 18 | Various Semiconductor, Adhesive Backed | 1.31 x 1.31 x .355 (33.27 x 33.27 x 9.02) | 16.10 | 294-1100-ND | 2.40 | 2.16 | 1.68 | BDN13-3CB/A01 | |
| | Various Semiconductor, Adhesive Backed | 1.41 x 1.41 x .355 (35.81 x 35.81 x 9.02) | 16.20 | 294-1101-ND | 3.71 | 3.34 | 2.60 | BDN14-3CB/A01 | |
| | Various Semiconductor, Adhesive Backed | 1.51 x 1.51 x .355 (38.35 x 38.35 x 9.02) | 15.10 | 294-1102-ND | 2.89 | 2.60 | 2.03 | BDN15-3CB/A01 | |
| | Various Semiconductor, Adhesive Backed | 1.61 x 1.61 x .355 (40.89 x 40.89 x 9.02) | 13.50 | 294-1103-ND | 2.96 | 2.67 | 2.08 | BDN16-3CB/A01 | |
| | Various Semiconductor, Adhesive Backed | 1.71 x 1.71 x .355 (43.43 x 43.43 x 9.02) | 11.50 | 294-1111-ND | 3.03 | 2.74 | 2.13 | BDN17-3CB/A01 | |
| | Various Semiconductor, Adhesive Backed | 1.81 x 1.81 x .355 (45.97 x 45.97 x 9.02) | 10.80 | 294-1104-ND | 3.22 | 2.90 | 2.25 | BDN18-3CB/A01 | |
| 19 | Various SMT Semiconductor | 1.026 x 1.026 x .457 (26.6 x 26.6 x 11.6) | 5.3 | 294-1125-ND | 3.34 | 3.01 | 2.34 | APR27-27-12CB | |
| | Various SMT Semiconductor, with Thermal Tape | 1.026 x 1.026 x .457 (26.6 x 26.6 x 11.6) | 5.3 | 294-1126-ND | 4.33 | 3.91 | 3.04 | APR27-27-12CB/A01 | |
| | Various SMT Semiconductor, with Short Clip | 1.026 x 1.026 x .457 (26.6 x 26.6 x 11.6) | 5.3 | 294-1127-ND | 4.54 | 4.09 | 3.18 | APR27-27-12CB/S | |
| | Various SMT Semiconductor, with Medium Clip | 1.026 x 1.026 x .457 (26.6 x 26.6 x 11.6) | 5.3 | 294-1128-ND | 4.54 | 4.09 | 3.18 | APR27-27-12CB/M | |
| | Various SMT Semiconductor, with Tall Clip | 1.026 x 1.026 x .457 (26.6 x 26.6 x 11.6) | 5.3 | 294-1129-ND | 4.54 | 4.09 | 3.18 | APR27-27-12CB/T | |
| | Various SMT Semiconductor | 1.284 x 1.284 x .457 (32.6 x 32.6 x 11.6) | 3.8 | 294-1130-ND | 3.74 | 3.37 | 2.62 | APR33-33-12CB | |
| | Various SMT Semiconductor, with Thermal Tape | 1.284 x 1.284 x .457 (32.6 x 32.6 x 11.6) | 3.8 | 294-1131-ND | 4.92 | 4.43 | 3.44 | APR33-33-12CB/A01 | |
| | Various SMT Semiconductor, with Short Clip | 1.284 x 1.284 x .457 (32.6 x 32.6 x 11.6) | 3.8 | 294-1132-ND | 4.96 | 4.46 | 3.47 | APR33-33-12CB/S | |
| | Various SMT Semiconductor, with Medium Clip | 1.284 x 1.284 x .457 (32.6 x 32.6 x 11.6) | 3.8 | 294-1133-ND | 4.96 | 4.46 | 3.47 | APR33-33-12CB/M | |
| | Various SMT Semiconductor, with Tall Clip | 1.284 x 1.284 x .457 (32.6 x 32.6 x 11.6) | 3.8 | 294-1134-ND | 4.96 | 4.46 | 3.47 | APR33-33-12CB/T | |
| | Various SMT Semiconductor | 1.461 x 1.461 x .457 (37.1 x 37.1 x 11.6) | 3.3 | 294-1135-ND | 3.85 | 3.47 | 2.70 | APR38-38-12CB | |
| | Various SMT Semiconductor, with Thermal Tape | 1.461 x 1.461 x .457 (37.1 x 37.1 x 11.6) | 3.3 | 294-1136-ND | 4.61 | 4.15 | 3.23 | APR38-38-12CB/A01 | |
| | Various SMT Semiconductor, with Short Clip | 1.461 x 1.461 x .457 (37.1 x 37.1 x 11.6) | 3.3 | 294-1137-ND | 5.05 | 4.55 | 3.54 | APR38-38-12CB/S | |
| | Various SMT Semiconductor, with Medium Clip | 1.461 x 1.461 x .457 (37.1 x 37.1 x 11.6) | 3.3 | 294-1138-ND | 5.05 | 4.55 | 3.54 | APR38-38-12CB/M | |
| | Various SMT Semiconductor, with Tall Clip | 1.461 x 1.461 x .457 (37.1 x 37.1 x 11.6) | 3.3 | 294-1139-ND | 5.05 | 4.55 | 3.54 | APR38-38-12CB/T | |
| | 20 | Heatsink Low-Profile Forged | .748 x .748 x .248 (19 x 19 x 6.3) | 7.05 | 294-1145-ND | 3.45 | 3.11 | 2.42 | APF19-19-06CB |
| | | Heatsink Forged with Adhesive Tape | .748 x .748 x .248 (19 x 19 x 6.3) | 7.05 | 294-1146-ND | 4.22 | 3.80 | 2.96 | APF19-19-06CB/A01 |
| | | Heatsink Low-Profile Forged | .748 x .748 x .374 (19 x 19 x 9.5) | 5.25 | 294-1147-ND | 3.48 | 3.14 | 2.44 | APF19-19-10CB |
| Heatsink Forged with Adhesive Tape | | .748 x .748 x .374 (19 x 19 x 9.5) | 5.25 | 294-1148-ND | 4.31 | 3.89 | 3.02 | APF19-19-10CB/A01 | |
| Heatsink Low-Profile Forged | | .748 x .748 x .500 (19 x 19 x 12.7) | 3.95 | 294-1149-ND | 4.31 | 3.89 | 3.02 | APF19-19-13CB | |
| Heatsink Forged with Adhesive Tape | | .748 x .748 x .500 (19 x 19 x 12.7) | 3.95 | 294-1150-ND | 4.31 | 3.89 | 3.02 | APF19-19-13CB/A01 | |
| Heatsink Low-Profile Forged | | 1.181 x 1.181 x .248 (30 x 30 x 6.3) | 4.35 | 294-1151-ND | 4.31 | 3.88 | 3.02 | APF30-30-06CB | |
| Heatsink Forged with Adhesive Tape | | 1.181 x 1.181 x .248 (30 x 30 x 6.3) | 4.35 | 294-1152-ND | 5.45 | 4.91 | 3.82 | APF30-30-06CB/A01 | |
| Heatsink Low-Profile Forged | | 1.181 x 1.181 x .374 (30 x 30 x 9.5) | 3.25 | 294-1153-ND | 4.45 | 4.01 | 3.12 | APF30-30-10CB | |
| Heatsink Forged with Adhesive Tape | | 1.181 x 1.181 x .374 (30 x 30 x 9.5) | 3.25 | 294-1154-ND | 5.62 | 5.06 | 3.94 | APF30-30-10CB/A01 | |
| Heatsink Low-Profile Forged | | 1.181 x 1.181 x .500 (30 x 30 x 12.7) | 2.45 | 294-1155-ND | 4.78 | 4.30 | 3.35 | APF30-30-13CB | |
| Heatsink Forged with Adhesive Tape | | 1.181 x 1.181 x .500 (30 x 30 x 12.7) | 2.45 | 294-1156-ND | 5.29 | 4.77 | 3.71 | APF30-30-13CB/A01 | |
| Heatsink Low-Profile Forged | | 1.575 x 1.575 x .248 (40 x 40 x 6.3) | 3.30 | 294-1157-ND | 5.74 | 5.17 | 4.02 | APF40-40-06CB | |
| Heatsink Forged with Adhesive Tape | | 1.575 x 1.575 x .248 (40 x 40 x 6.3) | 3.30 | 294-1158-ND | 5.88 | 5.30 | 4.12 | APF40-40-06CB/A01 | |
| Heatsink Low-Profile Forged | | 1.575 x 1.575 x .374 (40 x 40 x 9.5) | 2.50 | 294-1159-ND | 5.79 | 5.21 | 4.06 | APF40-40-10CB | |
| Heatsink Forged with Adhesive Tape | | 1.575 x 1.575 x .374 (40 x 40 x 9.5) | 2.50 | 294-1160-ND | 6.05 | 5.45 | 4.24 | APF40-40-10CB/A01 | |
| Heatsink Low-Profile Forged | | 1.575 x 1.575 x .500 (40 x 40 x 12.7) | 1.90 | 294-1161-ND | 5.98 | 5.39 | 4.19 | APF40-40-13CB | |
| Heatsink Forged with Adhesive Tape | | 1.575 x 1.575 x .500 (40 x 40 x 12.7) | 1.90 | 294-1162-ND | 6.61 | 5.95 | 4.63 | APF40-40-13CB/A01 | |

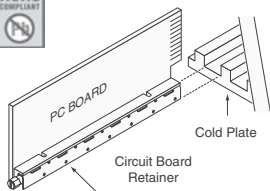
◆ RoHS Compliant

ZIF III Circuit Board Retainers

The ZIF retainer is a self-contained, precision assembly that provides highly effective thermal interface between the circuit board and cold plate. CTS ZIF III features a quick, quarter-turn locking mechanism that provides for a positive and fast assembly. The unique locking design produces a uniform pressure distribution along the PCB edge for optimal heat transfer and resistance to extreme shock and vibration.

Features:

- PCB board mountable (screw mounting)
- Positive 1/4 turn locking
- Field maintainable
- Superior mechanical retention
- Thermally efficient, 1.2°C-inch/Watt



| Description | Digi-Key Part No. | Price Each | | | CTS Part No. |
|---|----------------------|------------|-------|-------|-----------------|
| | | 1 | 10 | 100 | |
| PCB Retainer – Hex Head Drive, 4.50" Housing Assembly, Left Hand Part | 294-1163-ND | 48.09 | 40.08 | 35.40 | Z3A45SBSBNL |
| PCB Retainer – Hex Head Drive, 4.50" Housing Assembly, Right Hand Part | 294-1164-ND | 48.09 | 40.08 | 35.40 | Z3A45SBSBNR |
| PCB Retainer – Hex Head Drive, 5.25" Housing Assembly, Left Hand Part | 294-1165-ND | 50.35 | 41.96 | 37.07 | Z3A52SBSBNL |
| PCB Retainer – Hex Head Drive, 5.25" Housing Assembly, Right Hand Part | 294-1166-ND | 50.35 | 41.96 | 37.07 | Z3A52SBSBNR |

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